

# UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO
09/963,637	09/27/2001	Gary A. Brist	219.40432X00	9725
JAY P. BEALE c/o BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP 12400 WILSHIRE BOULEVARD, SEVENTH FLOOR LOS ANGELES, CA 90025			EXAMINER	
			PAK, SUNG H	
			ART UNIT	PAPER NUMBER
			2874	·····
			DATE MAILED: 07/15/2004	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)			
	09/963,637	BRIST ET AL.			
Office Action Summary	Examiner	Art Unit			
	Sung H. Pak	2874			
The MAILING DATE of this communica Period for Reply	tion appears on the cover sheet w	ith the correspondence address			
A SHORTENED STATUTORY PERIOD FOR THE MAILING DATE OF THIS COMMUNICA  - Extensions of time may be available under the provisions of 3 after SIX (6) MONTHS from the mailing date of this communic  - If the period for reply specified above is less than thirty (30) da  - If NO period for reply is specified above, the maximum statuto  - Failure to reply within the set or extended period for reply will,  Any reply received by the Office later than three months after earned patent term adjustment. See 37 CFR 1.704(b).	ATION. 7 CFR 1.136(a). In no event, however, may a cation. ays, a reply within the statutory minimum of thir up period will apply and will expire SIX (6) MON by statute, cause the application to become Al	reply be timely filed ty (30) days will be considered timely. NTHS from the mailing date of this communication. BANDONED (35 U.S.C. § 133).			
Status					
1) Responsive to communication(s) filed of	Responsive to communication(s) filed on 22 April 2004.				
2a) This action is <b>FINAL</b> . 2b)	This action is <b>FINAL</b> . 2b)⊠ This action is non-final.				
3) Since this application is in condition for	3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits				
closed in accordance with the practice	under <i>Ex parte Quayle</i> , 1935 C.D	). 11, 453 O.G. 213.			
Disposition of Claims					
4) ⊠ Claim(s) 1-19,21-26,28,30,32 and 34 is 4a) Of the above claim(s) is/are v 5) □ Claim(s) is/are allowed. 6) ⊠ Claim(s) 1-19,21-26,28,30,32 and 34 is. 7) □ Claim(s) is/are objected to. 8) □ Claim(s) are subject to restriction	vithdrawn from consideration. /are rejected.				
Application Papers					
9) The specification is objected to by the Entro  10) The drawing(s) filed on is/are: a)  Applicant may not request that any objection Replacement drawing sheet(s) including the should be	accepted or b) objected to not the drawing(s) be held in abeyar correction is required if the drawing.	nce. See 37 CFR 1.85(a). (s) is objected to. See 37 CFR 1.121(d).			
Priority under 35 U.S.C. § 119					
12) Acknowledgment is made of a claim for a) All b) Some * c) None of:  1. Certified copies of the priority doc 2. Certified copies of the priority doc 3. Copies of the certified copies of the application from the International	cuments have been received. cuments have been received in A ne priority documents have been Bureau (PCT Rule 17.2(a)).	pplication No received in this National Stage			
* See the attached detailed Office action fo	i a list of the certified copies not	receivea.			
Attachment(s)					
<ol> <li>Notice of References Cited (PTO-892)</li> <li>Notice of Draftsperson's Patent Drawing Review (PTO-3)</li> <li>Information Disclosure Statement(s) (PTO-1449 or PTO Paper No(s)/Mail Date</li> </ol>	948) Paper No(s	nummary (PTO-413) s)/Mail Date nformal Patent Application (PTO-152)			

#### **DETAILED ACTION**

Applicant's amendment filed 4/22/2004 has been entered, and all pending claims have been carefully reconsidered in view of the amendment. Claims 27, 29, 31, 33 are cancelled by this amendment, thus claims 1-19, 21-26, 28, 30, 32, 34 are now pending.

In light of the amended limitations and the remarks set forth in the amendment, the previous ground of rejection is withdrawn. However, upon further consideration a new ground of rejection is set forth based on a newly found prior art.

## Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).

Claims 1-8, 17-19, 21-26, 28, 30, 32 are rejected under 35 U.S.C. 103(a) as being unpatentable over Wojnarowski et al (US 5,562,838) in view of Hornbeck et al (US 6,387,284).

Art-Unit: 2874

Wojnarowski et al was cited in the previous office action.

As discussed in the previous office action, Wojnarowski discloses an optical device and a method of forming the optical device comprising: forming a trench in a substrate (Fig. 19A); providing at least one metalized surface along the trench (Fig. 19B, column 11 lines 32-33); activating a bonding material, such as adhesive ("248", column 12 lines 18-19); having a metalized capping surface (246, column 12 lines 16-17) to bond the bonding material to the substrate such that the metalized capping surface is located over the trench having at least one metalized surface (Fig. 19C); wherein the substrate comprises a printed circuit board (column 3 lines 12-29); wherein the substrate comprises a dielectric material (column 10 lines 17-18); wherein the trench is formed by selectively removing portions of the dielectric material (column 11 lines 65-67); wherein at least one metalized surface comprises sidewall surfaces and a bottom surface of a waveguide structure (Fig. 19B); wherein the metalized capping surface on the bonding material is formed by providing the bonding material and selectively placing the metalized capping surface on the bonding material (column 12 lines 13-19); filling the trench with a material (Fig. 17A-17B); wherein the bonding material is formed on top of the trench as a top surface ("248" Fig. 19C).

However, Wojnarowski does not explicitly teach that the metallized capping surface is located only over the trench.

Hornbeck teaches the use of metallized capping surface that is selectively removed such that it is located only over the trench of the waveguide (Figs. 8-10, column 8 lines 32-60, column 9 lines 12-18). Having a metallized capping surface only over the trench of a waveguide is

Art Unit: 2874

considered advantageous and desirable because this allows for a complete and more effective enclosure of waveguiding core having and thus results in low loss of transmitted optical signals.

Therefore, it would have been obvious to a person of ordinary skill in the art at the time the invention was made to modify the device in Wojnarowski to have a metallized capping surface that is selectively removed such that it is located only over the trench of the waveguide.

Claims 9-16 are rejected under 35 U.S.C. 103(a) as being unpatentable over Doi (US 6,539,157 B2) in view of Hornbeck et al (US 6,387,284).

Doi was cited in the previous office action.

As discussed in the previous office action, Doi discloses an optical device and a method of forming the optical device comprising: forming a trench in a printed circuit board substrate (abstract); the trench having a first side surface, a second side surface and a bottom surface (Fig.1); forming at least one surface on the first side surface, the second side surface and the bottom surface of the trench (column 4 lines 16-25); forming a capping surface ("30") on a bonding material (column 5 lines 52-60); forming the bonding material as a top surface over the trench having at least one surface, the top surface being different than said at least one surface (column 5 lines 41-51); wherein said at least one surface comprises at least one metalized surface and said top surface comprises a separate top metalized surface, wherein the capping surface is a metalized capping surface (column 5 lines 31-60); wherein the substrate comprises a dielectric material (column 2 lines 32-49); therein the trench is formed by selectively removing portions of the printed circuit board substrate (column 4 lines 40-57); wherein the metalized capping surface

on the bonding material is formed by applying a metal coating on the bonding material and selectively removing portions of the metal coating such that the metalized capping surface remains on the bonding material (column 5 lines 47-51).

However, Doi does not explicitly state that the metallized capping surface is located only over the trench.

Hornbeck teaches the use of metallized capping surface that is selectively removed such that it is located only over the trench of the waveguide (Figs. 8-10, column 8 lines 32-60, column 9 lines 12-18). Having a metallized capping surface only over the trench of a waveguide is considered advantageous and desirable because this allows for a complete and more effective enclosure of waveguiding core having and thus results in low loss of transmitted optical signals.

Therefore, it would have been obvious to a person of ordinary skill in the art at the time the invention was made to modify the device in Doi to have a metallized capping surface that is selectively removed such that it is located only over the trench of the waveguide.

## Response to Arguments

Starting on page 9 of the applicant's Remarks, it is argued that Wojnarowski does not teach placing the capping material only over the trench area as recited in the amended claims.

However, the examiner respectfully points out that a step of placing a metallized capping material only over the trench area is not a patentable feature as discussed in this office action.

Prior art, such as Hornbeck et al (US 6,387,284) discloses this feature, and the recited claims are rendered obvious as discussed above.

Also, it is argued that Doi shows portions of the cover that does not cover the trench, and that therefore Doi does not disclose a capping material that is located substantially only over the trench area.

The examiner respectfully points out that although Doi shows holes in the cover area that allow the passage of light, these holes take up very small portion of the cover (column 5 lines 40-47), and that the waveguiding core is indeed *substantially* covered. If the waveguiding core were not substantially covered, and that the holes were prominently distributed on the cover, the waveguiding portion 20 would not able to guide light waves, contrary to the teachings of Doi. Therefore, the recited limitations of the instant application is disclosed by Doi as discussed in this office action.

#### Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Sung H. Pak whose telephone number is (571) 272-2353. The examiner can normally be reached on Monday- Friday, 9AM-5PM.

The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Art Unit: 2874

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

An

Sung H. Pak Examiner Art Unit 2874